

IN THE SPECIFICATION

Please replace the paragraph beginning at page 1, line 7, with the following rewritten paragraph:

The build-up process is well known as a conventional method of manufacturing a multilayer circuit board. For example, a multilayer circuit board is manufactured as follows in this process. Firstly, via holes are formed at prescribed positions in a one-side copper-clad laminate manufactured by applying a copper foil to one side of an insulating substrate. The via holes are filled with an electrically conductive paste. A copper foil is bonded to the insulating substrate side of the one-side copper-clad laminate by pressing, and is etched so that a prescribed conductor circuit is formed.

Please replace the paragraph beginning at page 6, line 16, with the following rewritten paragraph:

The printed boards thus stacked are heated and pressed under vacuum at 180°C for 70 minutes so that the adhesive layer 11 is hardened, whereby the printed boards 2, 2A and 2B, and the outermost copper foil 6 are bonded together. The multilayer circuit board [[11]] 1 in which the printed boards 2, 2A and 2B and outermost copper foil 6 are integrated is manufactured by one pressing operation (FIG. 2(H)). The distal ends of the conductive bumps 9 of each printed board are connected to prescribed locations of the conductor circuit 10 on the adjacent printed board 2, whereupon the conductor circuits 10 of the adjacent printed boards 2 are electrically connected to each other.